



*From Nano to Micro Power Electronics
And Packaging Workshop
November the 28th, 2019
Tours, France
11th Edition*



TECHNICAL PROGRAMME

Technical Committee: Lars BÖTTCHER, Fraunhofer Institute IZM, Germany
Cyril BUTTAY, Ampère Laboratory, France
Guillaume CALLERANT, Sonceboz S.A., Switzerland
Jean-Luc DIOT, France
Franck DOSSEUL, Moduleus, France
Sébastien JACQUES, Greman Laboratory, France
Guo-Quan LU, Virginia Tech, USA
Jürgen SCHUDERER, ABB Corporate Research, Switzerland
Christophe SERRE, ST Microelectronics, France - Chairman
Daniel ALQUIER, Greman Laboratory, France - Chairman
Stéphane BELLENGER, éolane, France – General Chairman

8 h 30 Workshop package and badge distribution

9 h 00 Welcome and full day workshop program presentation

9 h 15 Keynotes: Power Module Packaging, Market & Technology trends, Speaker invitee

10 h 05 Coffee break / Table Top Exhibition and presentation

10 h 35 Session 1: Design & Applications

10 h 35 AC/DC power converter using a high voltage high speed package for an integrated GaN circuit – Dominique Bergogne – CEA-Leti, France, Grenoble Alps University, France

11 h 00 Cold Lamination Tests of Grooved Internal Cavities in LTCC for Thermal Management – Malika Tililil – IMT Atlantique Lab-Stice CNRS, Brest, France

11 h 25 A new research center enabling the next generation of power electronics – Gari Arutinov - CITC/TNO, Nijmegen, The Netherlands

11 h 50 Packaging for multi-die integration of GaN transistors in application under 1 kW – Johan Delaine – CEA-Leti, France, Grenoble Alps University, France

12 h 15 Table Top Exhibition visit and Lunch (Buffet)

13 h 30 Session 2: Materials, Processes & Technologies

13 h 30 Die Bonding Power Packaging Solutions – Jonathan Abdilla – BESI Austria GmbH, Austria

13 h 55 Virtual Metrology for a Magnetron Sputtering Machine in Photovoltaic Cell Manufacturing – Guglielmo Montone – Wex Fab, Paris, France

14 h 20 Optimization of the manufacturing process of macro and nano structures for power modules' interconnection – Thomas Dias – Laboratoire Laplace, Toulouse, France

14 h 45 *Coffee break / Table Top Exhibition*

15 h 15 **Session 2 con't: Materials, Processes & Technologies**

15 h 15 Reconfigurability of active ultrasound sensors through FOPLP approaches – Guillaume Ferrin – Vermon S.A., Tours, France

15 h 40 **Session 3: Quality & Reliability**

15 h 40 DBC to Baseplate Attach: A novel Reinforced Matrix Solder Solution for Increased Reliability – Karthirk Vijay – Indium Corporation, UK

16 h 05 *Coffee break / Table Top Exhibition*

16 h 30 **Session 3 con't: Quality & Reliability**

16 h 30 Surface preparation in Power Device Manufacturing – Gilbert Lecarpentier – Ontos Equipment Systems, Chester, NH, USA

16 h 55 Pressure-less sintering for power semiconductor devices – Giovanni Salvatore – ABB Research, Baden, Switzerland

17 h 20 **End of session**

Next to the workshop sessions of Thursday, November the 28th, an exceptional event will be organized to close the workshop day for which you need to register if you wish to attend:

- ***A visit of a famous Loire's attractive site. Departure from Greman's institute at 17h30***
- ***A dinner in a gastronomic restaurant around 20h00***

On Friday, November the 29th, a specific GREMAN lab tour is organized, starting at 9:00

Sponsors:



From Nano to Macro Power Electronics and Packaging European Workshop

28 November 2019 Thursday

GREMAN (ECOLE D'INGENIEURS POLYTECH TOURS)
Amphithéâtre du département électronique et énergie 7 avenue Marcel Dassault Tours

Registration Form
Final registration Thursday November the 26th 2019

COMPANY:

NAME:

FIRSTNAME:

ADDRESS:

TEL:

E-MAIL:

→Send back to Florence Vireton by E-mail: imaps.france@imapsfrance.org

FEEES (including conferences attendance, table top visit, lunch, coffee breaks, social event and closing dinner)

Conferences on free access on website www.imapsfrance.org after the event.

- IMAPS MEMBER 220 € HT excluding - 264 € TTC
- Non IMAPS MEMBER 250 € HT – 300.00 € TTC
- SPEAKERS/CHAIRS 180 € HT - 216 € TTC
- Table Top 300 € HT – 360.00 € TTC (1 table, chairs, display panel, conferences attendance, Coffee breaks, lunch, social event and closing dinner).

For foreign companies, VAT is excluded

Do not forget to tick boxes if you want to participate to our social event

- Visit of a typical Touraine castle (Thursday evening) yes no
- Dinner after the visit (Thursday evening) yes no

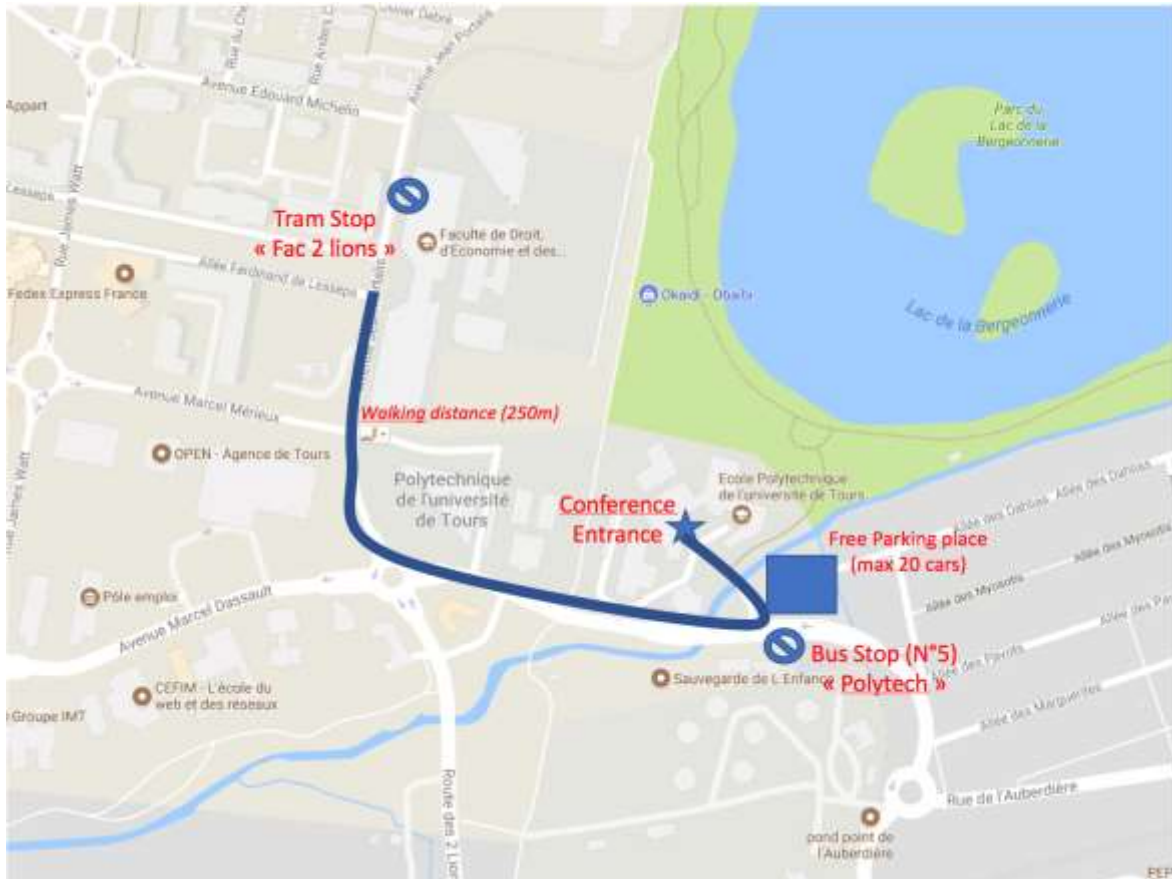
- On line Payment and Registration available on www.france.imapseurope.org

PAYMENT BANK REFERENCES

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International Microelectronics and Packaging Society – France
17 rue de l'Amiral Hamelin 75016 Paris France Phone: +33 (0)1 45 05 72 32
+33 (07 88 75 59 86
E-mail : imaps.france@imapsfrance.org

How to reach GREMAN



Access by car from the A10 motorway

In the Paris-Bordeaux direction,

Take the exit n ° 22 Saint-Avertin, then follow the direction of the 2 Lions.

In the Bordeaux-Paris direction,

Take the exit n ° 23, follow the direction Tours-Center then the 2 Lions direction

Access by train and tram or bus

You can either go to the Tours train station which is in the city center or to the Saint Pierre des Corps railway station which is on the outskirts and which has both rail shuttles to Tours and buses to different points of the city . More info on the website of Fil Bleu.

Access to Polytech Tours by tram stop "Fac 2 Lions" or by bus by line 5 stop "Polytech".